

# CANTI® RF Cantilever

## Probe Cards

Although cantilever probe card technology has been an integral part of semiconductor wafer test programs for years, a reliable and affordable cantilever based RF solution has been noticeably missing. CANTI® RF probe card technology targets applications requiring a cost-effective and production worthy epoxy based probe card that can effectively deliver RF test signals.

CANTI® RF probe card is a hybrid of the TLPA (Transmission Line Probe Assembly) and very short probe technologies. The goal of CANTI® RF is to provide a lower cost that can handle RF test rates.

### RF PROBING

CANTI® RF probe cards can be manufactured with 2 to 16 RF lines. RF signals enter and exit the probe card via blindmate connectors. The RF usually has an accompanying ground probe from the PCB to the device under test (DUT) to ensure RF signal isolation.

A test rates capability of 1.2 Gbps to 6.0 Gbps makes the CANTI® RF the ideal production probe card for which operate in the low RF range.

Production lead times for CANTI® RF probe card are similar to standard cantilever probe cards.

CANTI® RF probe card technology will be the “at speed” wafer test solution for wireless semiconductor manufacturers worldwide.

### PERFORMANCE SPECIFICATIONS

Picth	100 µm for RF pads (adjacent pads) 80 µm for std. probes
Tip Shape/Diameter	Flat/18 µm (0.7 mil)
Probe Material	Rhenium Tungsten
Overdrive	50-75 µm (2-3 mils) recommended
Operating Temp.	Ambient to 150° C
Bandwidth	5.5 to 11.0 GHz @ -3dB
Rise Time	150 to 200 ps @ 20-80%
RF line Impedance	50 ohms to within 100 mils of the die pad
Tip Depth	100 mils Standard

### FEATURES:

Fully grounded probe ring

Total Rf probe length <.250”

Probe ring extends over the probes for increased isolation and grounding

Blindmate RF connectors (styles vary interface application)